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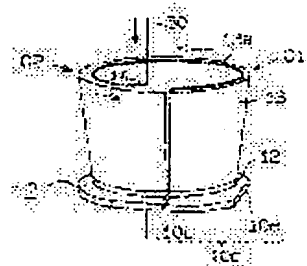
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## (54) METHOD AND APPARATUS FOR MANUFACTURING SEMICONDUCTOR SUBSTRATE

## (57)Abstract:

PROBLEM TO BE SOLVED: To provide a method for manufacturing a semiconductor substrate capable of stably manufacturing a high quality semiconductor substrate in spite of a hardness of a material to be used as a semiconductor ingot, and to provide a manufacturing apparatus used for the manufacturing method.

SOLUTION: The semiconductor ingot 13 is manufactured by fixing a semiconductor seed crystal 12 on the seating 10 and by growing the crystal from the fixed seed crystal 12. The semiconductor ingot 13 is cut to an optional shape and size by a wire electric discharge machining based on the seating with the seed crystal 12 and the semiconductor ingot 13 fixed on the seating 10.



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